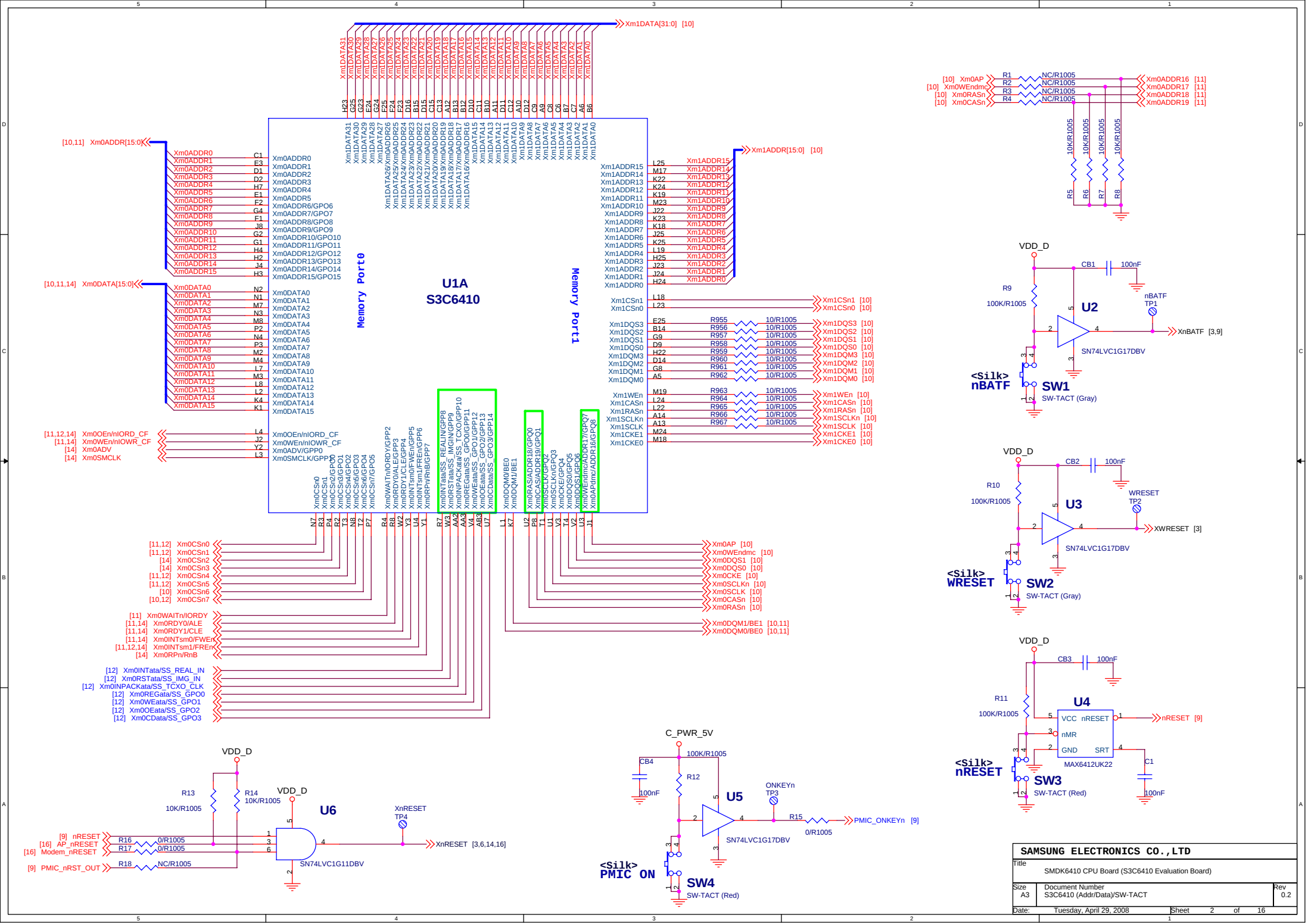
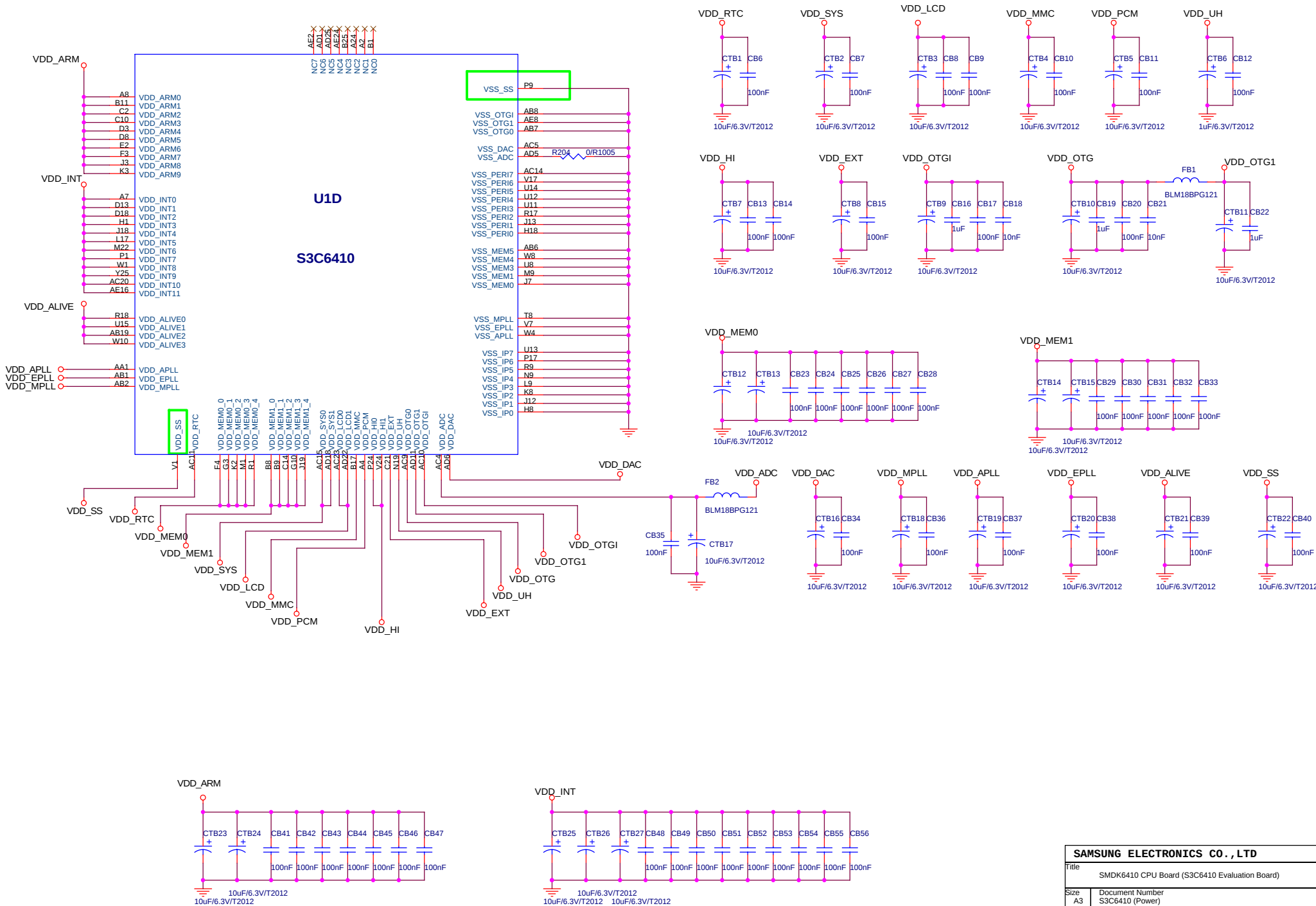


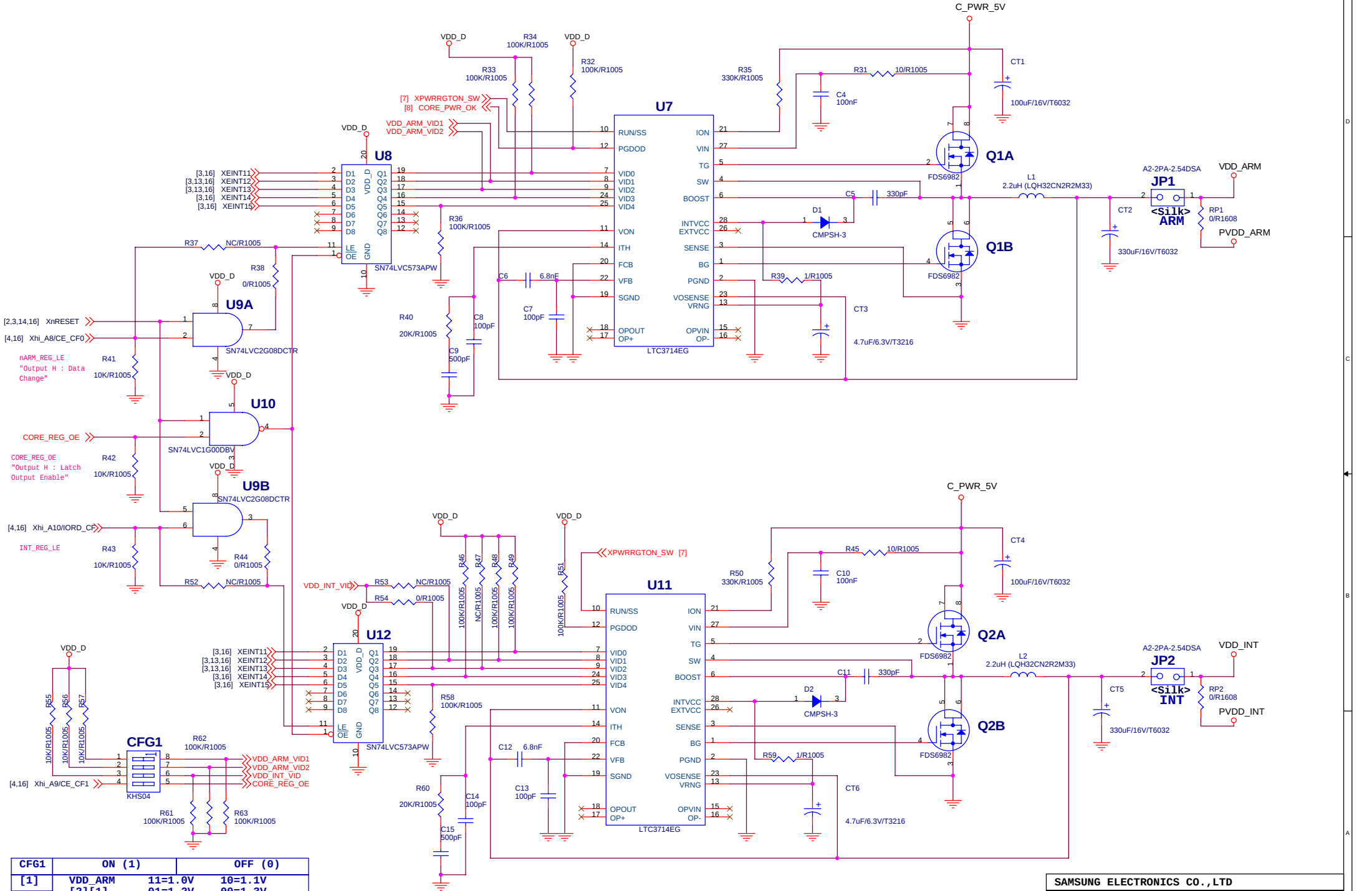
SMDK6410 CPU B'd (S3C6410 Evaluation Board) Schematics

Revision	Date	Description
Rev 0.0	2008. 02.20	Preliminary Version
Rev 0.1	2008. 04.02	Second Version (Refer to Sheet 2,4,6,7,8,9,13,14 and 15)
Rev 0.2	2008. 04.30	Third Version (Refer to Sheet 3, 8, 9 and 10)

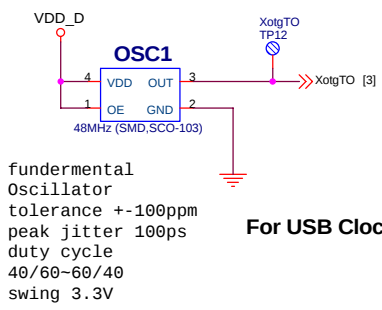
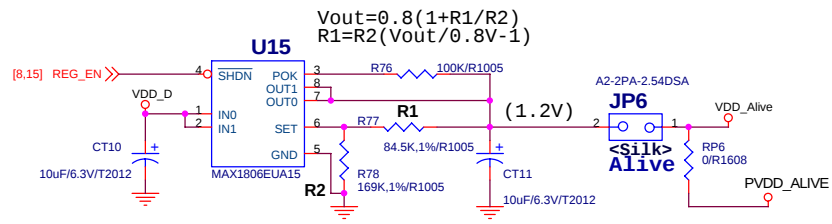
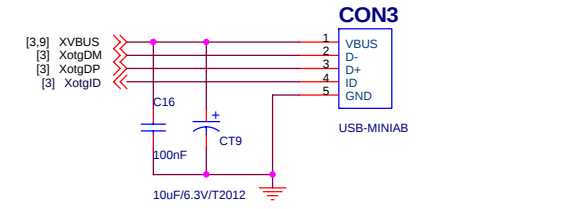
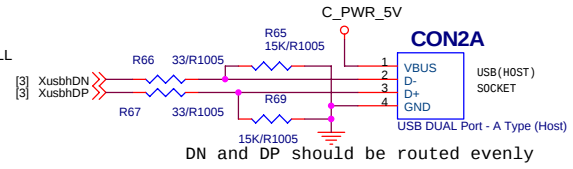
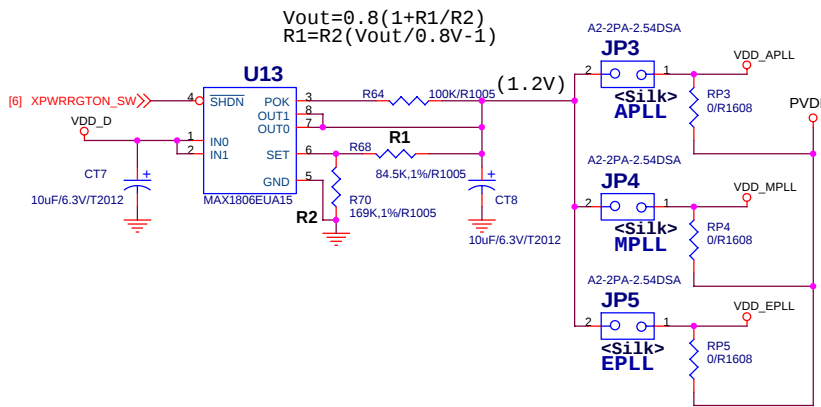
Table of Contents		Part Reference
Page	Function	<Component><Number>
01	Revision History	U : Component or Regurator IC
02	S3C6410 (Addr/Data)/SW-TACT	C : Capacitor
03	S3C6410 (I/O 1)	CB : Capacitor Bypass
04	S3C6410 (I/O 2)/ADC	CT : Capacitor Tantal
05	S3C6410 (Power)	CTB : Capacitor Tantal Bypass
06	Power (ARM,INT)	J : Jumper
07	Power (PLL,Alive,RTC)/USB Host/USB OTG	JB : CPU or Base connector
08	Power (I/O)	JP : Jumper Power
09	PMIC Socket	R : Resistor
10	Memory (mDDR)	RA : Resistor Array
11	Buffers (SROM IF)	RP : Resistor Power
12	Buffers Control (SROM IF)	VR : Variable Resistor
13	SD_MMC/SPI	L : Inductor
14	oneNAND/MIPI/JTAG/CLK	FB : Ferrite Bead
15	Camera Interface	OSC : Oscillator
16	B2B Connector	X : X-tal (Crystal)
		Q : Transistor or FET
		D : Diode
		ZD : Zener Diode
		LED : LED Diode
		SW : SWitch Tact/Push
		CON : CONnector
		CFG : ConFiGure switch (DIP/Slide)
		TP : Test Point (SMD)
		TPH : Test Point Hole (Through Hole)
		MTH: Mount Through Hole
		MOD : MODule Interface connector





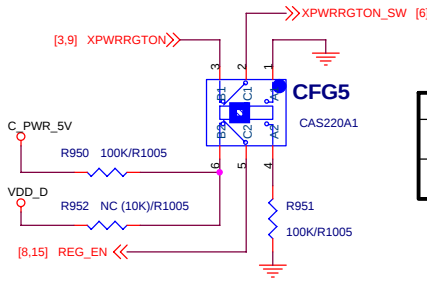
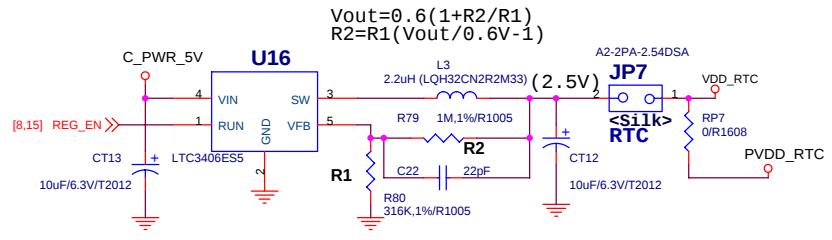
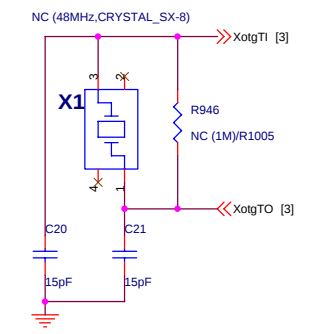


CFG1	ON (1)	OFF (0)
[1]	VDD_ARM 11=1.0V [2][1] 01=1.2V	10=1.1V 00=1.3V
[3]	VDD_INT 1.0V	VDD_INT 1.2V
[4]	PWRControl Enable	PWRControl Disable

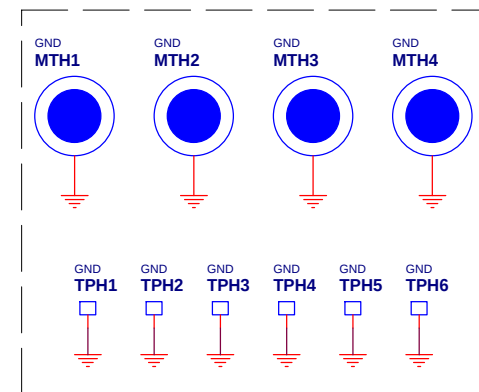
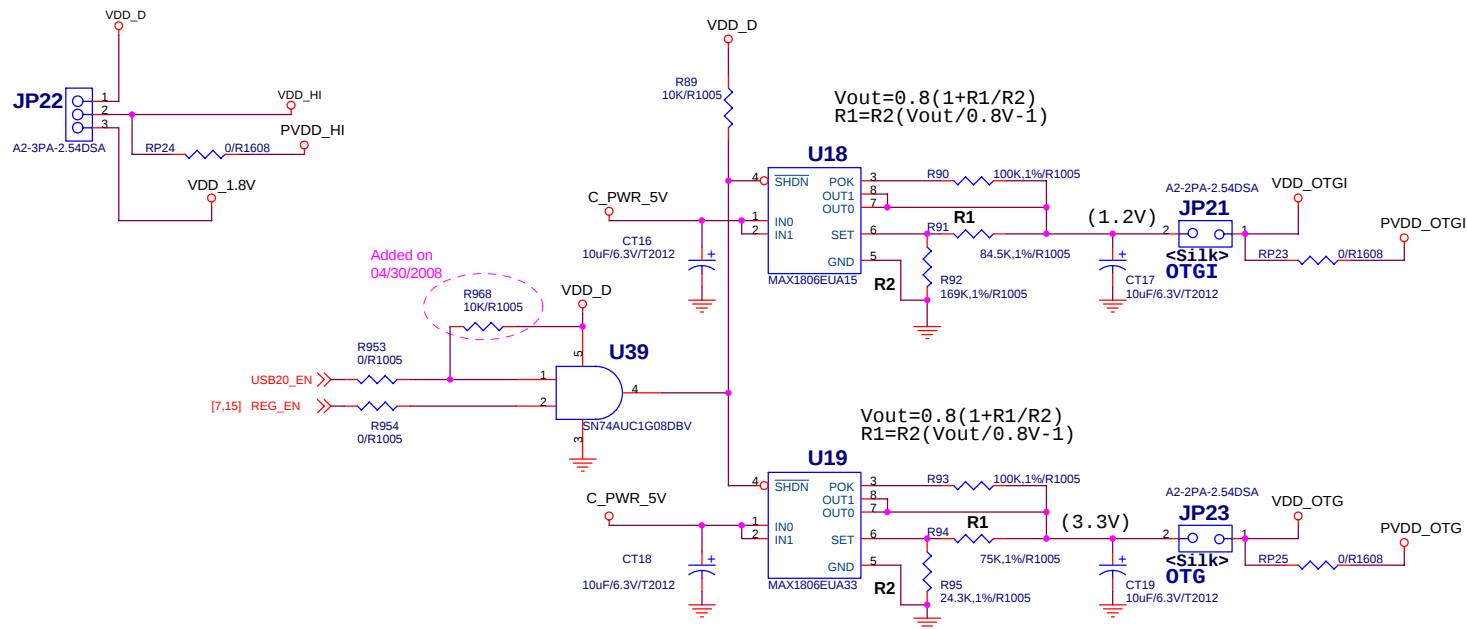
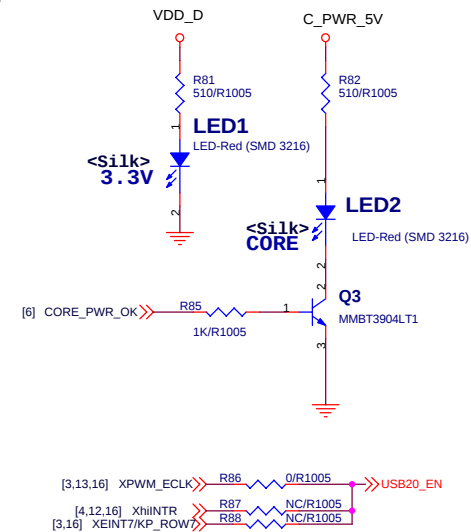
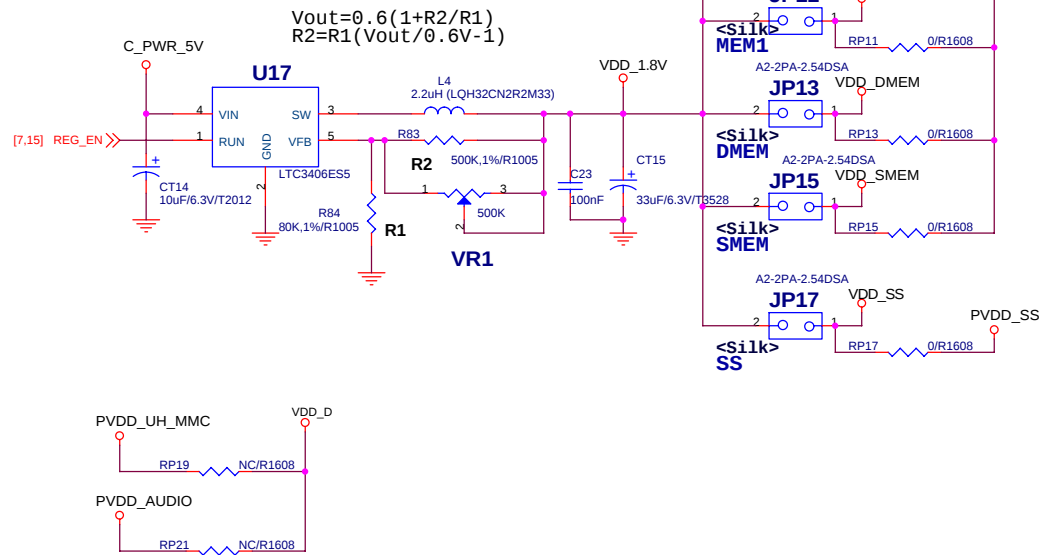
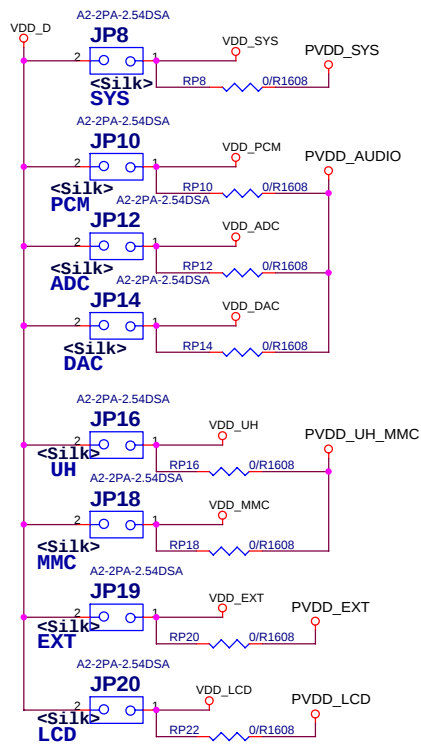


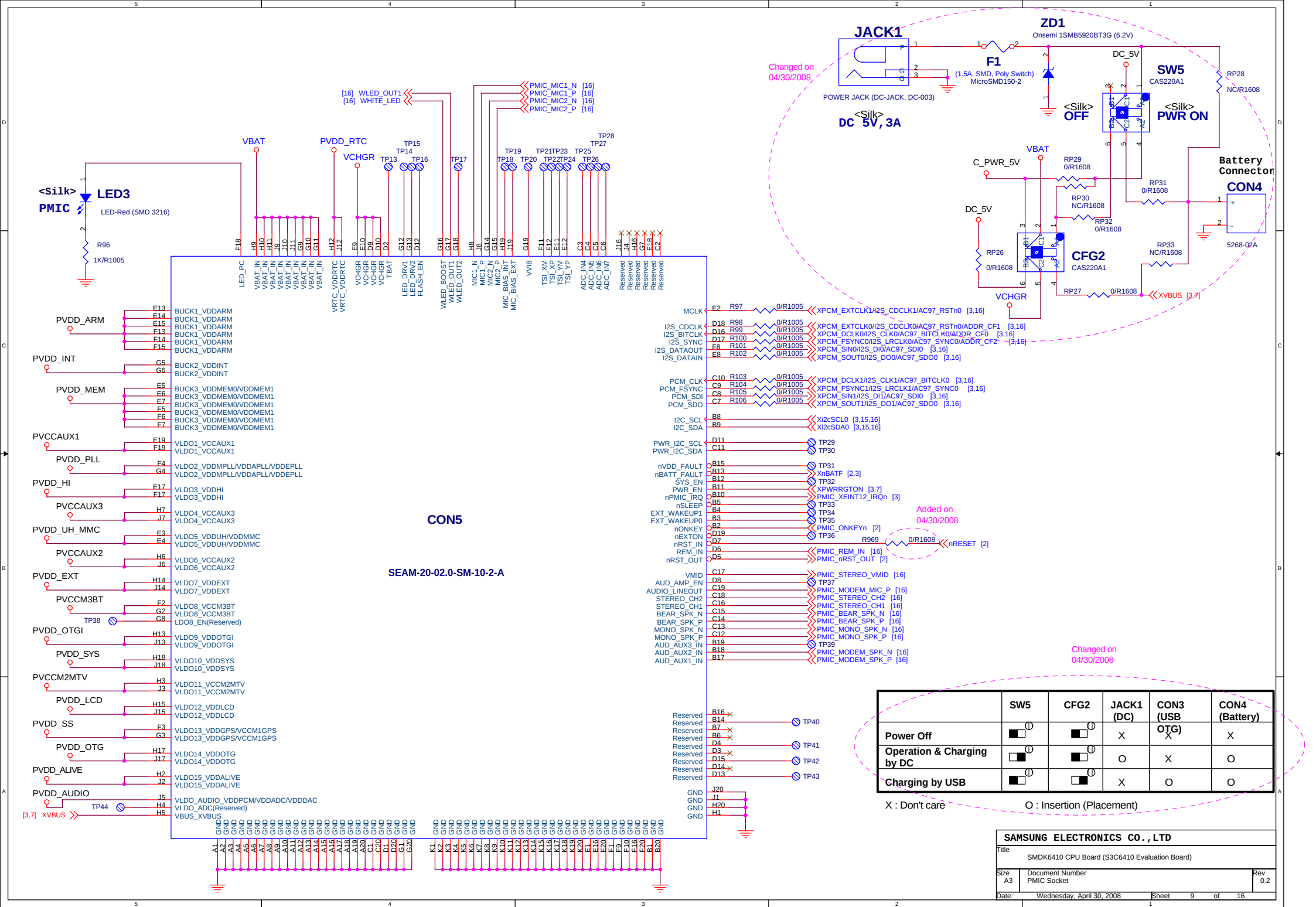
[3] XREXT

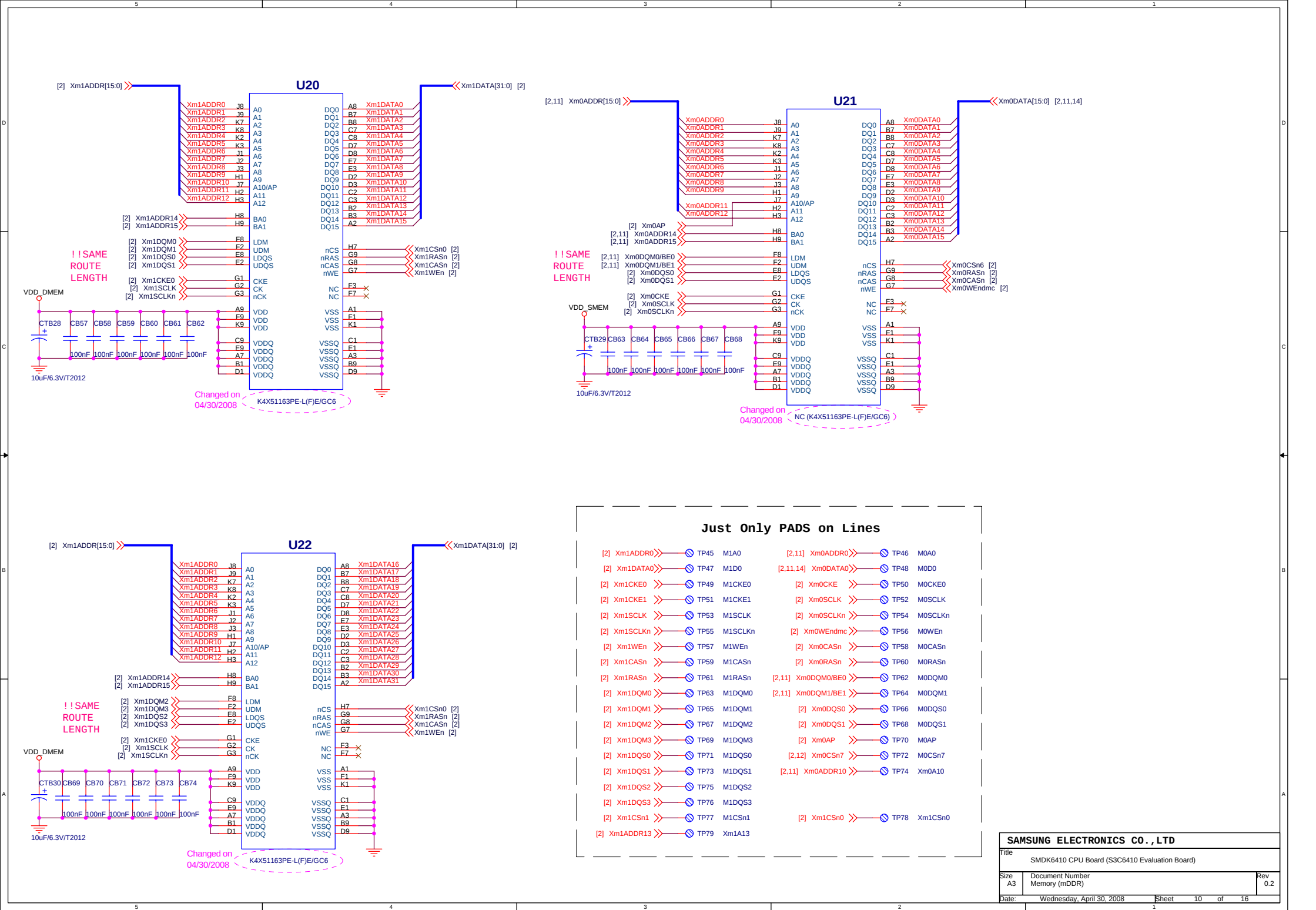
S3C6400 : 3.4K, 1%
 S3C6410 : 44.2 ohm, 1%
 ohm, 1%

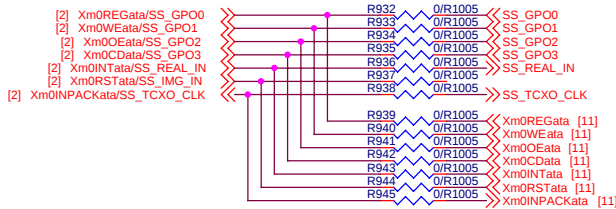
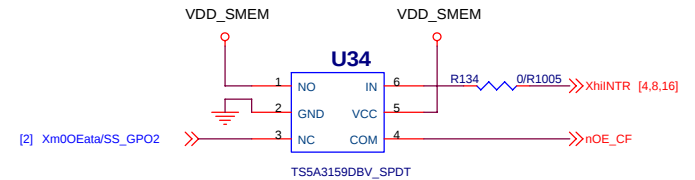
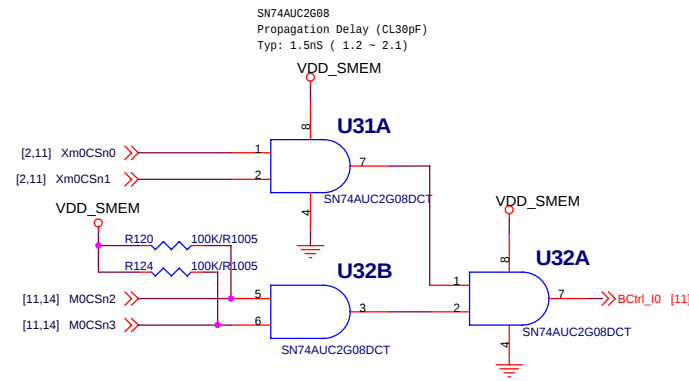
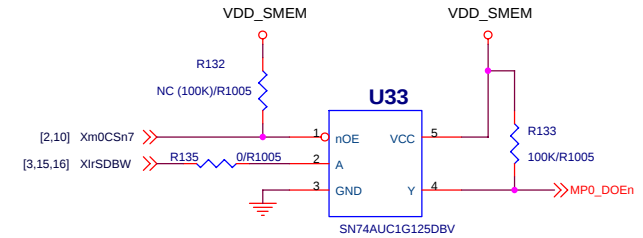
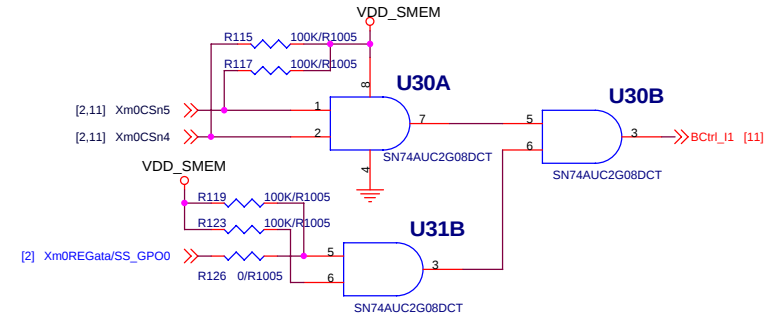
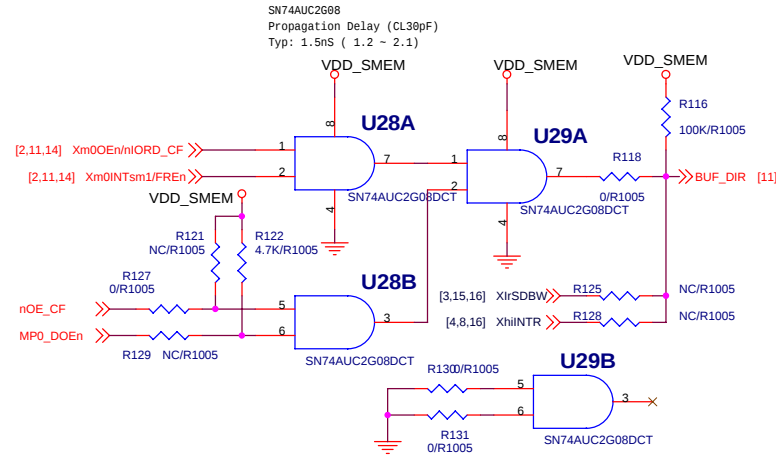
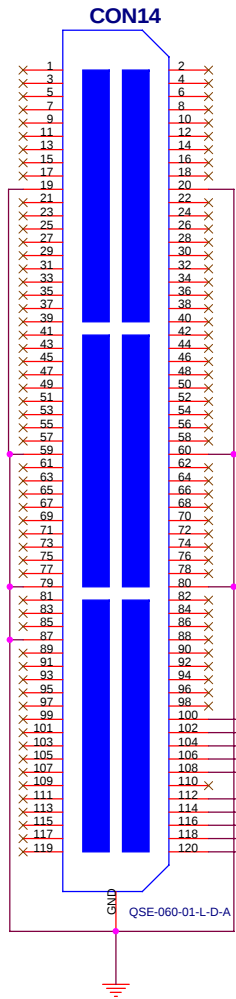


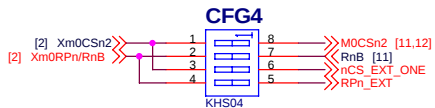
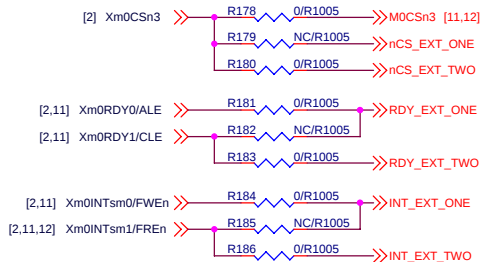
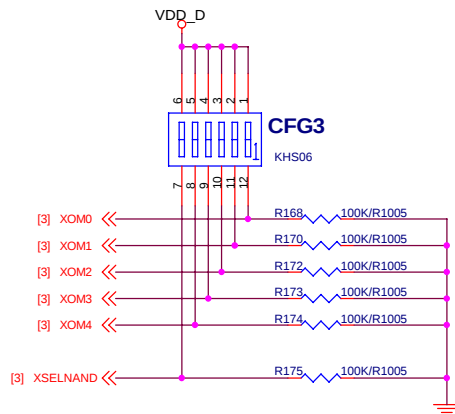
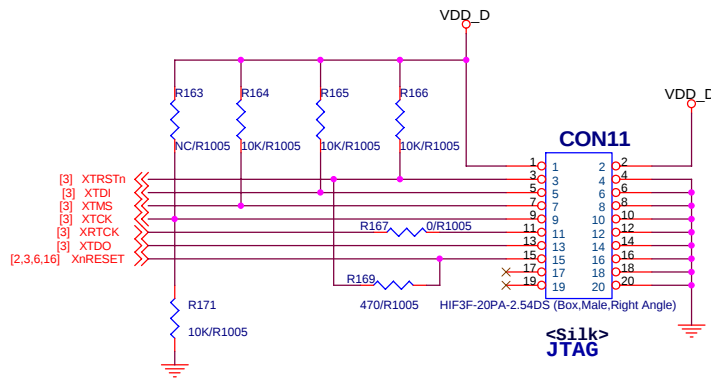
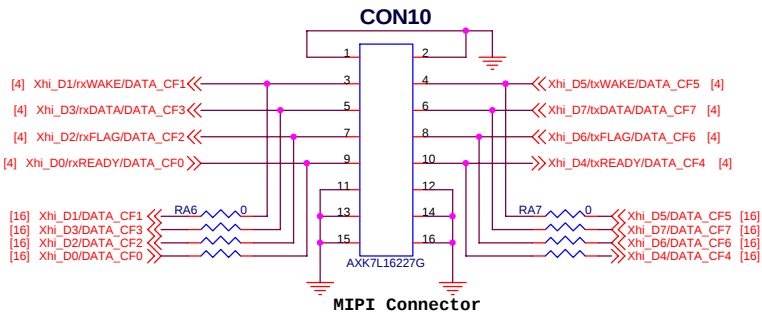
CFG5	
☐	Use PMIC
☒	Use Adapter



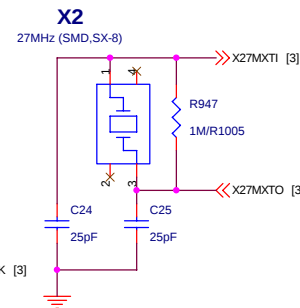
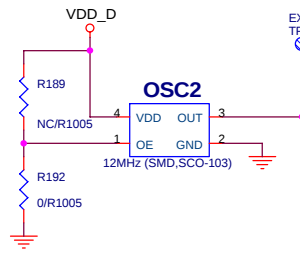
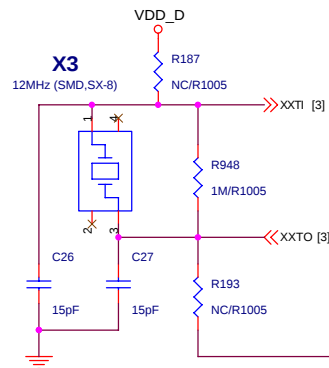
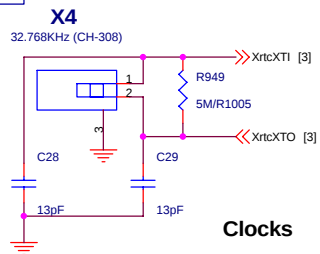
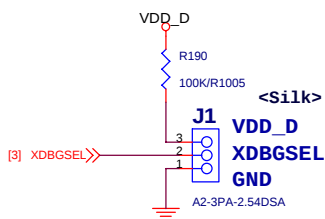








CFG4	NAND/ONENAND
[1, 2] : ON	NAND(CS2)
[3, 4] : OFF	OneNAND(CS2)

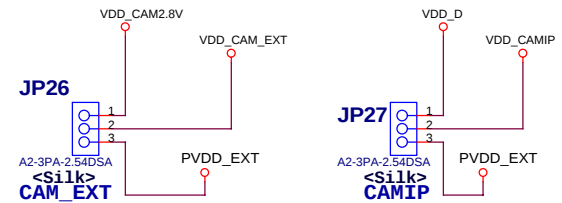
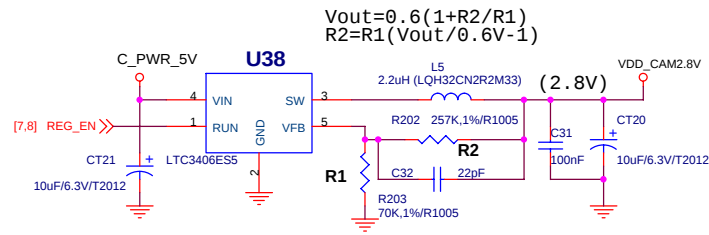
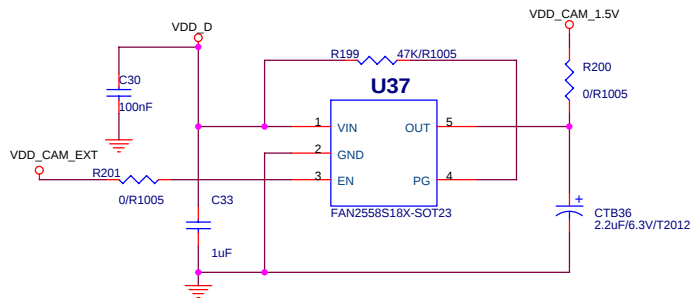
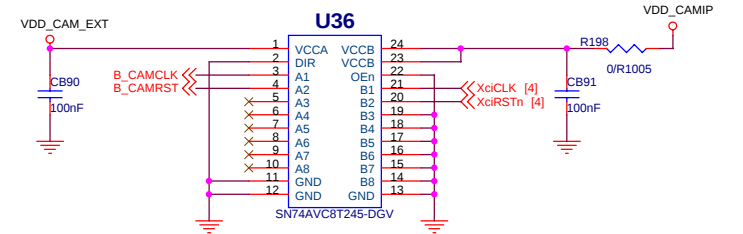
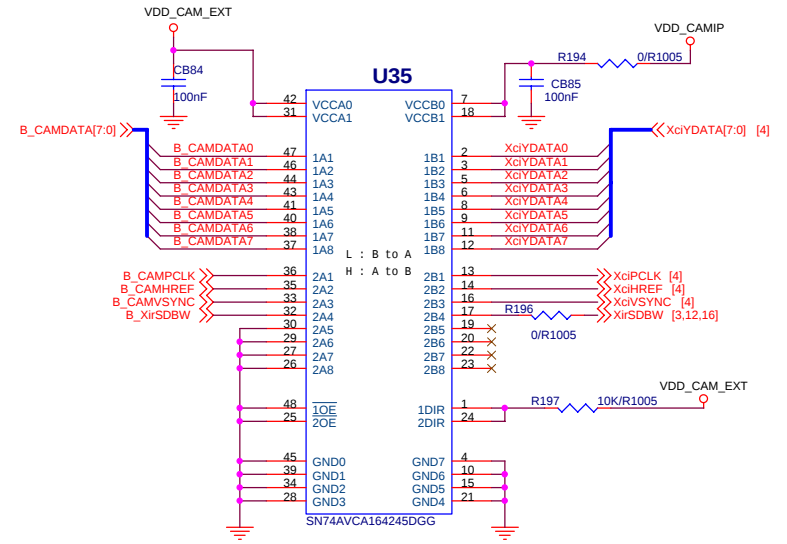
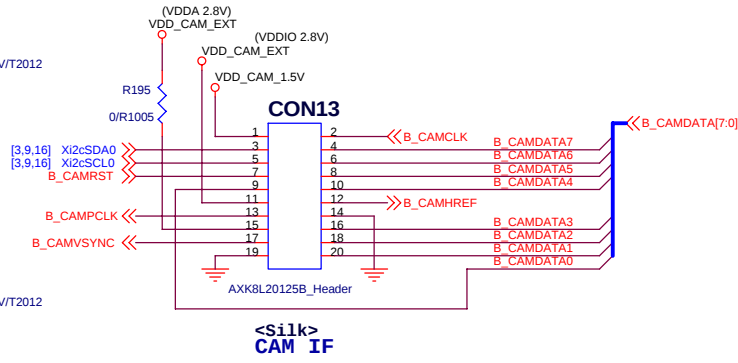
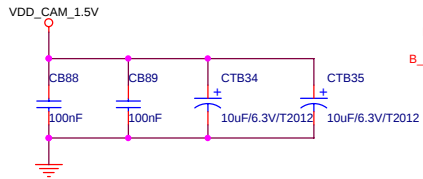
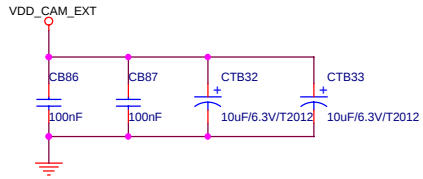


Booting Mode	[6]	[5]	[4]	[3]	[2]	[1]
NAND, 512/3 cycle	1	0	0	0	0	
NAND, 512/4 cycle	1	0	0	0	1	
ANAND, 2K/4 cycle	1	0	0	1	0	
ANAND, 2K/5 cycle	1	0	0	1	1	
NOR/SROM	x	0	1	0	0	
OneNAND	0	0	1	1	0	
Modem	x	0	1	1	1	
Internal ROM	x	1	1	1	1	

Camera Interface

B_XirSDBW >> TP85 B_XirSDBW
B_CAMCLK >> TP87 B_CAMCLK
B_CAMVSYNC >> TP89 B_CAMVSYNC
B_CAMHREF >> TP91 B_CAMHREF

B_CAMDATA0 >> TP86 B_CAMDATA0
B_CAMDATA1 >> TP88 B_CAMDATA1
B_CAMDATA2 >> TP90 B_CAMDATA2
B_CAMDATA3 >> TP92 B_CAMDATA3
B_CAMDATA4 >> TP93 B_CAMDATA4
B_CAMDATA5 >> TP94 B_CAMDATA5
B_CAMDATA6 >> TP95 B_CAMDATA6
B_CAMDATA7 >> TP96 B_CAMDATA7



SAMSUNG ELECTRONICS CO.,LTD			
Title			
SMDK6410 CPU Board (S3C6410 Evaluation Board)			
Size			
A3	Document Number	Camera Interface	Rev 0.2
Date: Tuesday, April 29, 2008			
Sheet 15 of 16			

